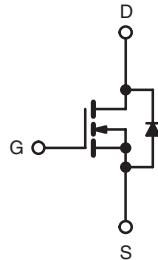
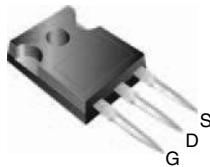


## Power MOSFET

PRODUCT SUMMARY	
$V_{DS}$ (V)	500
$R_{DS(on)}$ ( $\Omega$ )	$V_{GS} = 10\text{ V}$ 0.190
$Q_g$ (Max.) (nC)	150
$Q_{gs}$ (nC)	44
$Q_{gd}$ (nC)	72
Configuration	Single

TO-247



N-Channel MOSFET

### FEATURES

- Superfast Body Diode Eliminates the Need for External Diodes in ZVS Applications
- Lower Gate Charge Results in Simpler Drive Requirements
- Enhanced  $dV/dt$  Capabilities Offer Improved Ruggedness
- Higher Gate Voltage Threshold Offers Improved Noise Immunity
- Lead (Pb)-free Available



Available

**RoHS\***  
COMPLIANT

### APPLICATIONS

- Zero Voltage Switching SMPS
- Telecom and Server Power Supplies
- Uninterruptible Power Supplies
- Motor Control Applications

ORDERING INFORMATION	
Package	TO-247
Lead (Pb)-free	IRFP23N50LPbF
	SiHFP23N50L-E3
SnPb	IRFP23N50L
	SiHFP23N50L


ABSOLUTE MAXIMUM RATINGS $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted				
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	$V_{DS}$	500	V	
Gate-Source Voltage	$V_{GS}$	$\pm 30$		
Continuous Drain Current	$V_{GS}$ at 10 V	$T_C = 25\text{ }^\circ\text{C}$	23	A
		$T_C = 100\text{ }^\circ\text{C}$	15	
Pulsed Drain Current <sup>a</sup>	$I_{DM}$	92		
Linear Derating Factor		2.9	W/ $^\circ\text{C}$	
Single Pulse Avalanche Energy <sup>b</sup>	$E_{AS}$	410	mJ	
Repetitive Avalanche Current <sup>a</sup>	$I_{AR}$	23	A	
Repetitive Avalanche Energy <sup>a</sup>	$E_{AR}$	37	mJ	
Maximum Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	$P_D$	370	W
Peak Diode Recovery $dV/dt^c$		$dV/dt$	14	V/ns
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	- 55 to + 150	$^\circ\text{C}$
Soldering Recommendations (Peak Temperature)	for 10 s		300 <sup>d</sup>	
Mounting Torque	6-32 or M3 screw		10	lbf · in
			1.1	N · m

#### Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Starting  $T_J = 25\text{ }^\circ\text{C}$ ,  $L = 1.5\text{ mH}$ ,  $R_G = 25\text{ }\Omega$ ,  $I_{AS} = 23\text{ A}$  (see fig. 12).
- $I_{SD} \leq 23\text{ A}$ ,  $dI/dt \leq 430\text{ A}/\mu\text{s}$ ,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 150\text{ }^\circ\text{C}$ .
- 1.6 mm from case.

\* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	$R_{thJA}$	-	40	°C/W
Case-to-Sink, Flat, Greased Surface	$R_{thCS}$	0.24	-	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	0.34	

SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	500	-	-	V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$ , $I_D = 1\text{ mA}^d$	-	0.27	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	3.0	-	5.0	V
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 30\text{ V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 500\text{ V}, V_{GS} = 0\text{ V}$	-	-	50	$\mu\text{A}$
		$V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	-	2.0	mA
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 14\text{ A}^b$	-	0.190	0.235	$\Omega$
Forward Transconductance	$g_{fs}$	$V_{DS} = 50\text{ V}, I_D = 14\text{ A}^b$	12	-	-	S
<b>Dynamic</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V},$ $V_{DS} = 25\text{ V},$ $f = 1.0\text{ MHz}$ , see fig. 5	-	3600	-	pF
Output Capacitance	$C_{oss}$		-	380	-	
Reverse Transfer Capacitance	$C_{rss}$		-	37	-	
Output Capacitance	$C_{oss}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 1.0\text{ V}, f = 1.0\text{ MHz}$	-	4800	-
Effective Output Capacitance	$C_{oss\text{ eff.}}$		$V_{DS} = 400\text{ V}, f = 1.0\text{ MHz}$	-	100	-
Effective Output Capacitance (Energy Related)	$C_{oss\text{ eff. (ER)}}$		$V_{DS} = 0\text{ V to } 400\text{ V}^c$	-	220	-
			$V_{DS} = 0\text{ V to } 400\text{ V}^d$	-	160	-
Internal Gate Resistance	$R_G$	$f = 1\text{ MHz}$ , open drain	-	1.2	-	$\Omega$
Total Gate Charge	$Q_g$	$V_{GS} = 10\text{ V},$ $I_D = 23\text{ A}, V_{DS} = 400\text{ V}$ see fig. 6 and 13 <sup>b</sup>	-	-	150	nC
Gate-Source Charge	$Q_{gs}$		-	-	44	
Gate-Drain Charge	$Q_{gd}$		-	-	72	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 250\text{ V}, I_D = 23\text{ A}$ $R_G = 6.0, V_{GS} = 10\text{ V}$ see fig. 10 <sup>b</sup>	-	26	-	ns
Rise Time	$t_r$		-	94	-	
Turn-Off Delay Time	$t_{d(off)}$		-	53	-	
Fall Time	$t_f$		-	45	-	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source-Drain Diode Current	$I_S$	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	23	A
Pulsed Diode Forward Current <sup>a</sup>	$I_{SM}$		-	-	92	
Body Diode Voltage	$V_{SD}$	$T_J = 25\text{ }^\circ\text{C}, I_S = 14\text{ A}, V_{GS} = 0\text{ V}^b$	-	-	1.5	V
Body Diode Reverse Recovery Time	$t_{rr}$	$T_J = 25\text{ }^\circ\text{C}$	-	170	250	ns
		$T_J = 125\text{ }^\circ\text{C}$	-	220	330	
Body Diode Reverse Recovery Charge	$Q_{rr}$	$T_J = 25\text{ }^\circ\text{C}$	-	560	840	$\mu\text{C}$
		$T_J = 125\text{ }^\circ\text{C}$	-	980	1500	
Reverse Recovery Current	$I_{RRM}$	$T_J = 25\text{ }^\circ\text{C}$	-	7.6	11	A
Forward Turn-On Time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )				

### Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$ .
- $C_{oss\text{ eff.}}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{DS}$ .
- $C_{oss\text{ eff. (ER)}}$  is a fixed capacitance that stores the same energy time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{DS}$ .

## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

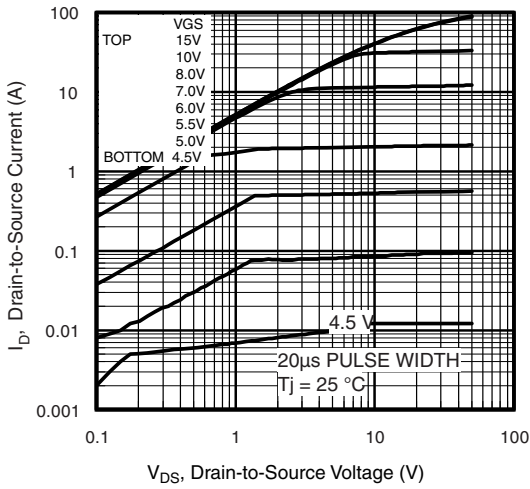


Fig. 1 - Typical Output Characteristics

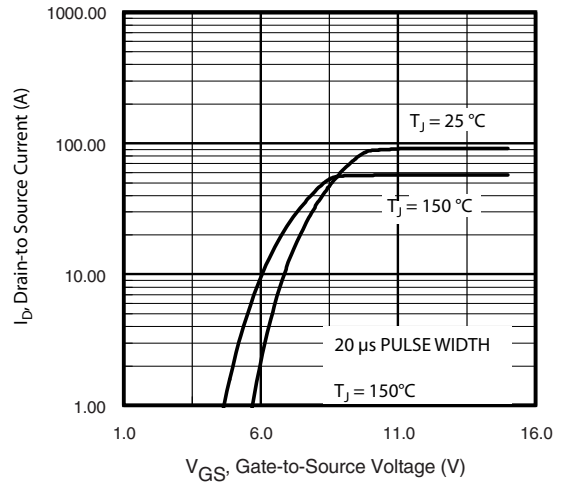


Fig. 3 - Typical Transfer Characteristics

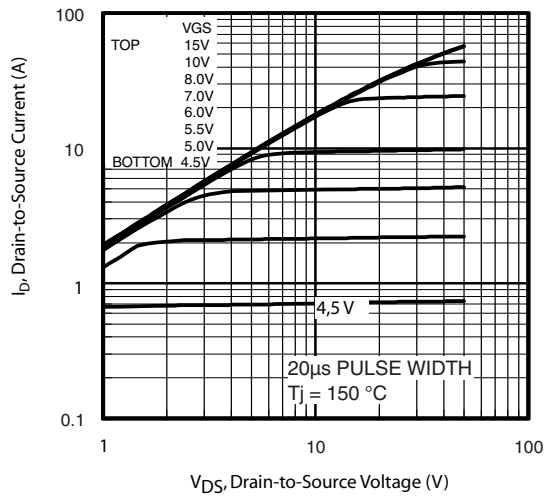


Fig. 2 - Typical Output Characteristics

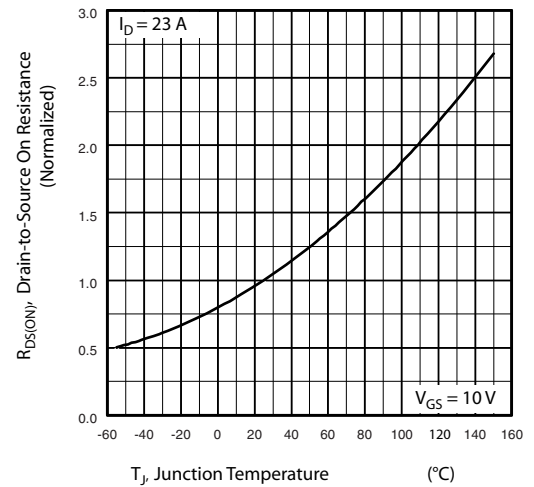
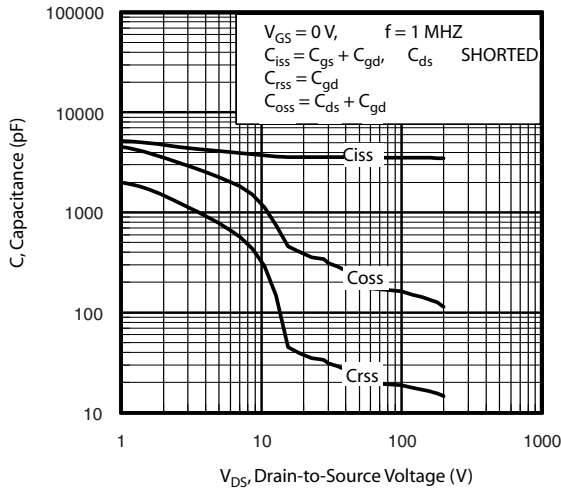
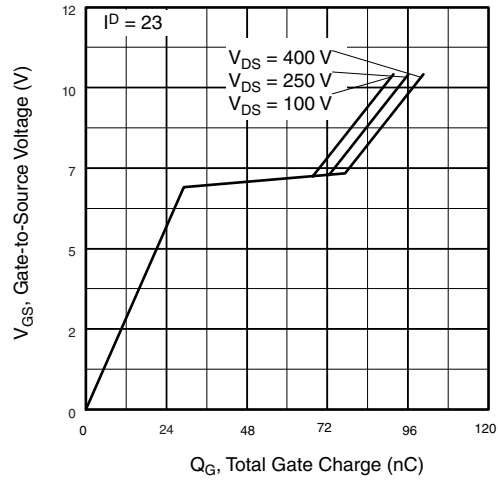


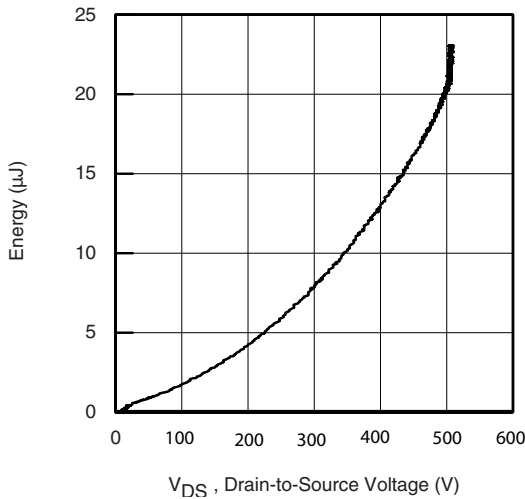
Fig. 4 - Normalized On-Resistance vs. Temperature



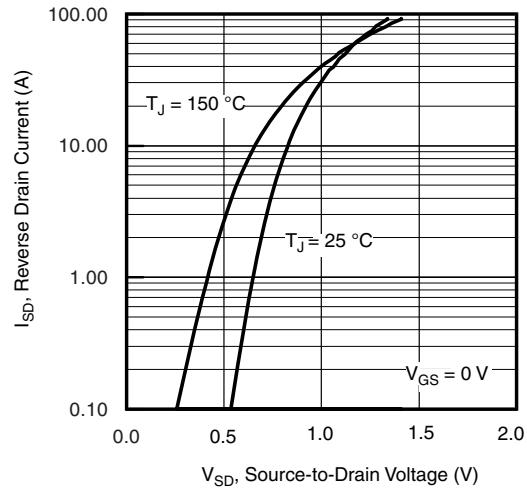
**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**



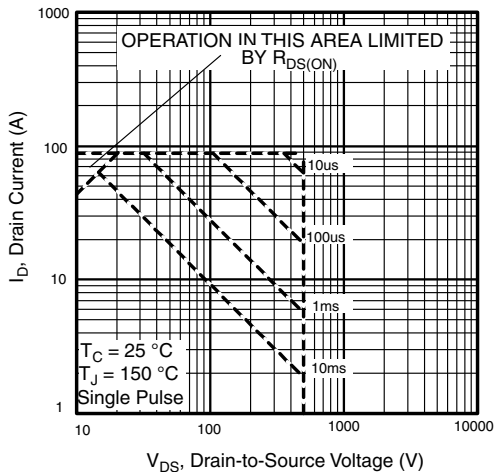
**Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage**



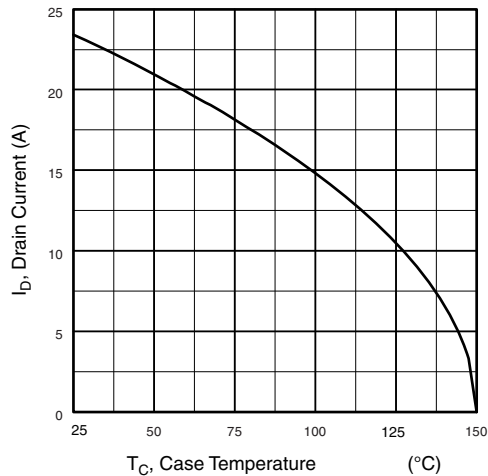
**Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage**



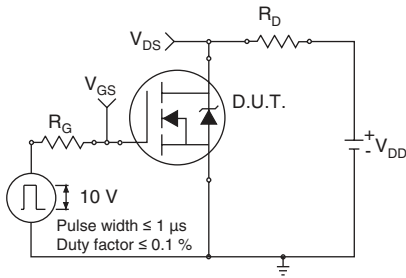
**Fig. 8 - Typical Source-Drain Diode Forward Voltage**



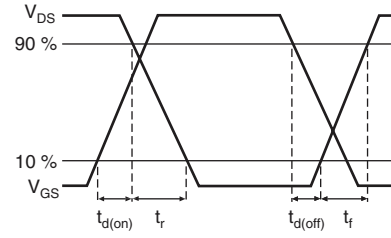
**Fig. 9 - Maximum Safe Operating Area**



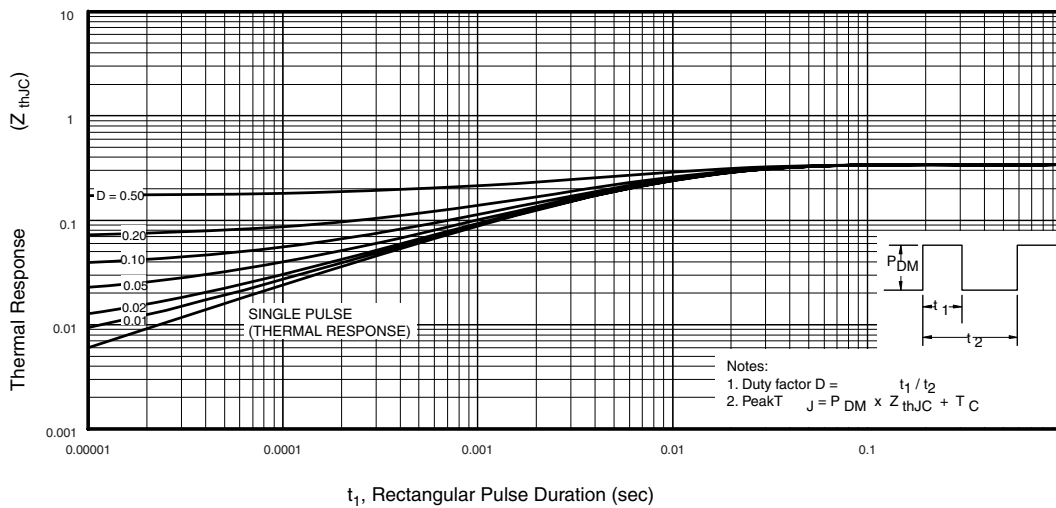
**Fig. 10 - Maximum Drain Current vs. Case Temperature**



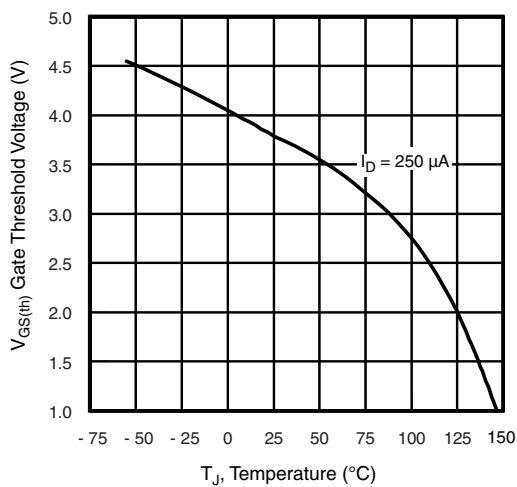
**Fig. 11a - Switching Time Test Circuit**



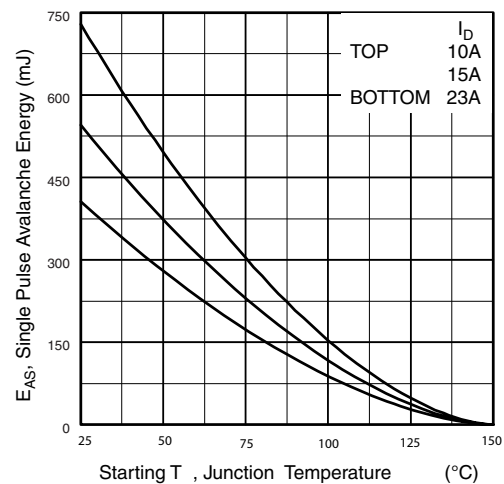
**Fig. 11b - Switching Time Waveforms**



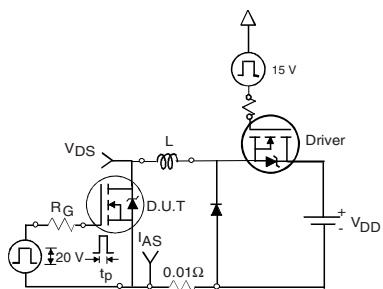
**Fig. 12 - Maximum Effective Transient Thermal Impedance, Junction-to-Case**



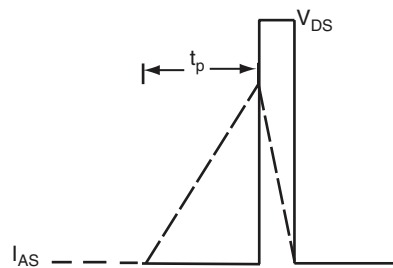
**Fig. 13 - Threshold Voltage vs. Temperature**



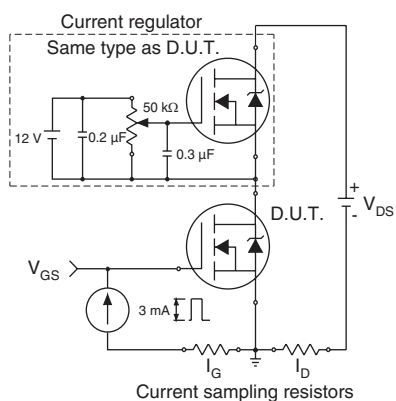
**Fig. 14 - Maximum Avalanche Energy s. Drain Current**



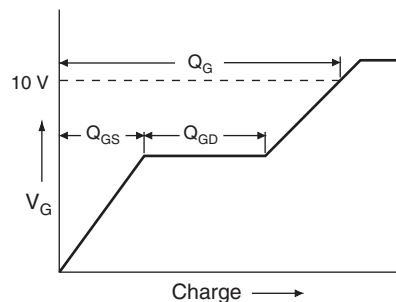
**Fig. 15a - Unclamped Inductive Test Circuit**



**Fig. 15b - Unclamped Inductive Waveforms**

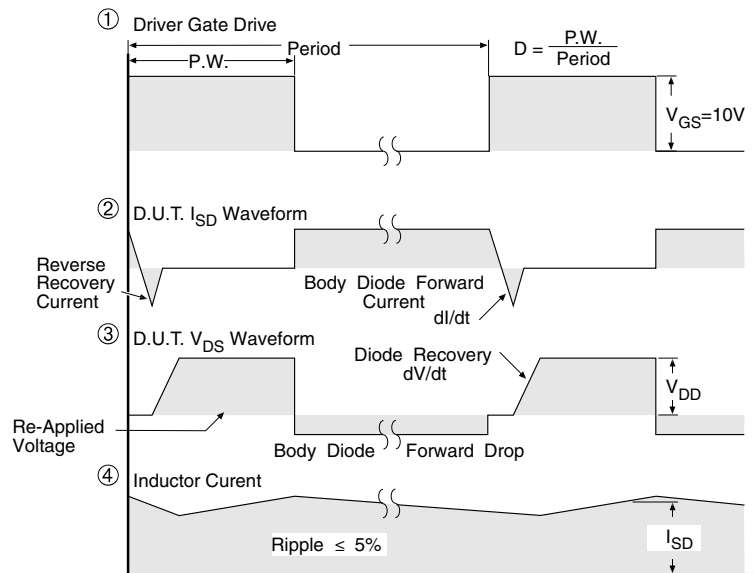
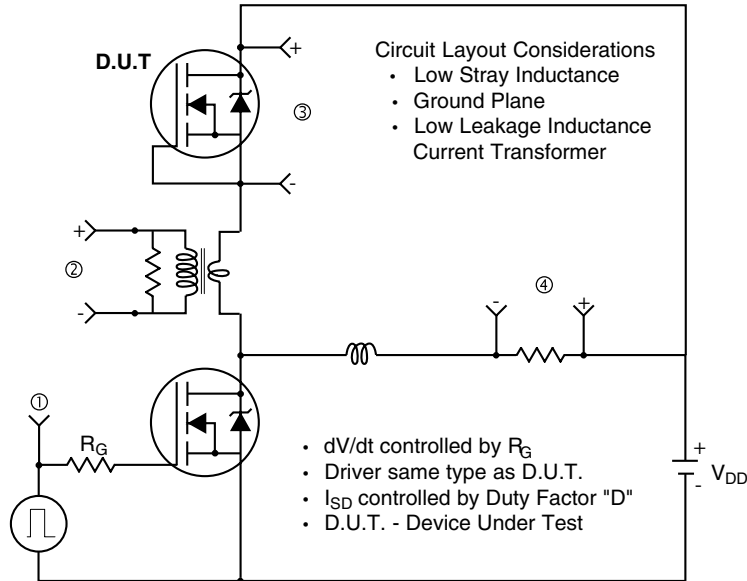


**Fig. 16a - Gate Charge Test Circuit**



**Fig. 16b - Basic Gate Charge Waveform**

## Peak Diode Recovery $dV/dt$ Test Circuit



\*  $V_{GS} = 5V$  for Logic Level Devices

Fig. 17 - For N-Channel

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